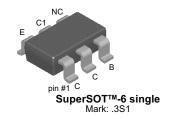


### **FMBS5551**

### **NPN General Purpose Amplifier**

• This device is designed for general purpose high voltage amplifiers and gas discharge display drivers.



## **Absolute Maximum Ratings\*** $T_a$ =25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{CEO}$	Collector-Emitter Voltage	160	V
V <sub>CBO</sub>	Collector-Base Voltage	180	V
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V
I <sub>C</sub>	Collector Current - Continuous	600	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
  These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Electrical Characteristics Ta=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Characte	Off Characteristics				
V <sub>(BR)CEO</sub>	Collector-Emitter Sustaining Voltage *	I <sub>C</sub> = 1.0mA, I <sub>B</sub> = 0	160		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_{C} = 100 \mu A, I_{E} = 0$	180		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10\mu A, I_C = 0$	6.0		V
I <sub>CBO</sub>	Collector Cutoff Current	$V_{CB} = 120V, I_{E} = 0$ $V_{CB} = 120V, I_{E} = 0, T_{a} = 100^{\circ}C$		50 50	nA μA
I <sub>EBO</sub>	Emitter Cut-off Current	V <sub>EB</sub> = 4.0V, I <sub>C</sub> = 0		50	nA
On Characte	eristics				
h <sub>FE</sub>	DC Current Gain	$I_C = 1.0 \text{mA}, V_{CE} = 5.0 \text{V}$ $I_C = 10 \text{mA}, V_{CE} = 5.0 \text{V}$ $I_C = 50 \text{mA}, V_{CE} = 5.0 \text{V}$	80 80 30	250	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA		0.15 0.2	V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA		1.0 1.0	V
Small Signal Characteristics					
f <sub>T</sub>	Current Gain Bandwidth Product	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 10, f = 100MHz	100	300	MHz
C <sub>obo</sub>	Output Capacitance	V <sub>CE</sub> = 10V, I <sub>C</sub> = 0, f = 1.0MHz		6.0	pF
C <sub>ibo</sub>	Input Capacitance	$V_{BE} = 0.5V, I_{C} = 0, f = 1.0MHz$		20	pF
h <sub>fe</sub>	Small Single Current Gain	I <sub>C</sub> = 1.0mA, V <sub>CE</sub> = 10V, f = 1.0KHz	50	250	
N <sub>F</sub>	Noise Figure	$I_C$ = 250μA, $V_{CE}$ = 5.0V, $R_S$ = 1.0KΩ, f = 10 Hz to 15.7KHz		8.0	dB

<sup>\*</sup> Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

Symbol	Parameter	May
Thermal (	Characteristics T <sub>a</sub> =25°C unless otherwise noted	

Symbol	Parameter	Max.	Units	
P <sub>D</sub>	Total Device Dissipation *	700	mW	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, total	180	°C/W	

<sup>\*</sup> Device mounted on a 1 in 2 pad of 2 oz copper.

## **Typical Characteristics**

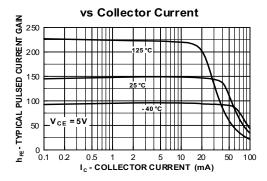


Figure 1. Typical Pulsed Current Gain vs Collector Current

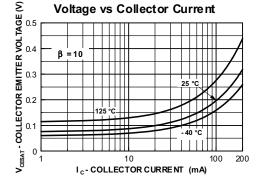


Figure 2. Collector-Emitter Saturation Voltage vs Collector Current

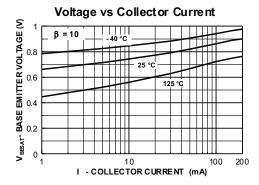


Figure 3. Base-Emitter Saturation Voltage vs Collector Current

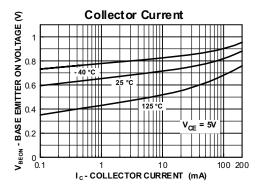


Figure 4. Base-Emitter On Voltage vs Collector Current

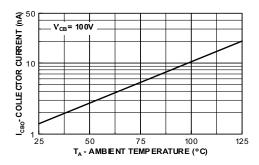


Figure 5. Collector Cutoff Current vs Ambient Temperature

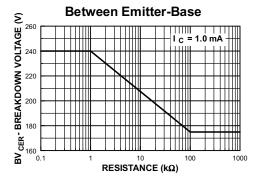


Figure 6. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base

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# Typical Characteristics (Continued)

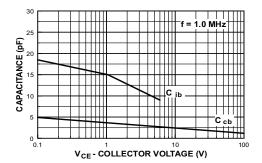


Figure 7. Input and Output Capacitance vs Reverse Voltage

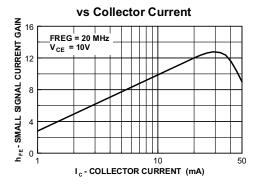
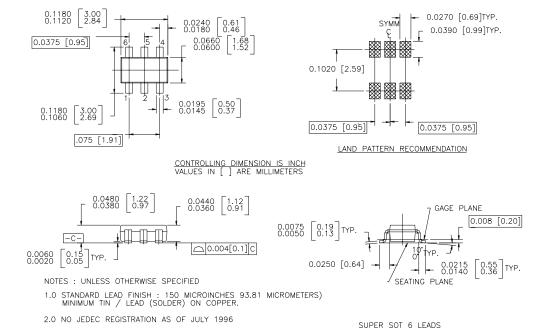


Figure 8. Small Signal current Gain vs Collector Current

# **Package Dimensions**

# SuperSOT™-6



Dimensions in Millimeters

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E <sup>2</sup> CMOS™	I <sup>2</sup> C™	MSXPro™	Quiet Series™	TINYOPTO™
EnSigna™	i-Lo™	OCX™	RapidConfigure™	TruTranslation™
FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
FACT Quiet Series™		OPTOLOGIC <sup>®</sup>	μSerDes™	UltraFET <sup>®</sup>
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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

### PRODUCT STATUS DEFINITIONS

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